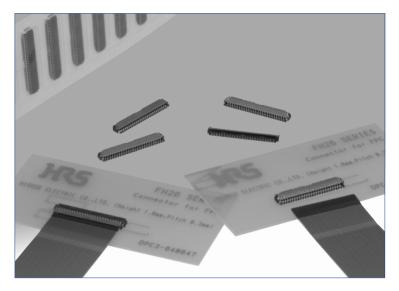
# 0.3mm Contact Pitch, 1mm above the board, Flexible Printed Circuit ZIF Connectors

### FH26 Series



#### Features

1. Extremely light weight

The typical version, with all 51 contacts loaded, weights only 0.1 grams.

- 2. Easy solderability on the PC board The soldering leads are on 0.6 mm pitch, exiting on front and back of the connector.
- 3. Conductive traces on the PCB can run under the connector

No exposed contacts on the bottom of the connector.

4. Easy FPC insertion and reliable electrical connection

Proven Flip LockR actuator allows easy insertion of FPC. Tactile sensation when fully closed confirms complete electrical and mechanical connection.

5. Accepts standard thickness FPC

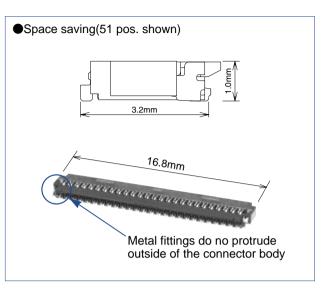
0.2mm thick standard Flexible Printed Circuit board can be used.

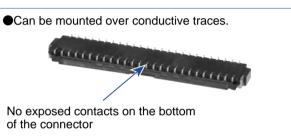
This is the only ultra-low profile ZIF connector allowing the use of standard FPC.

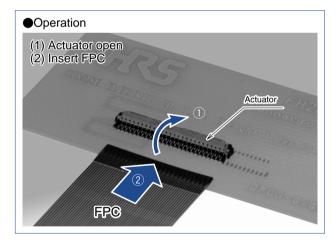
6. Board placement with automatic equipment Flat top surface and packaging on the tape-and-reel allows use of vacuum nozzles. Standard reel contains 5,000 connectors.

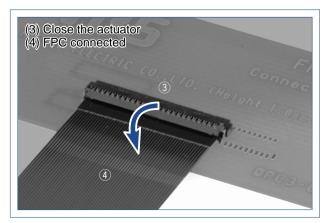
### Applications

Mobile phones, PDA's, digital cameras, digital video cameras, LCD connections, plasma displays (PDP), camera modules and other compact devices requiring Flexible Printed Circuit connections using high reliability ultra-small profile connectors.









### ■Specifications

Rating Current rating Voltage rating 0.2A DC 30V AC Operating temperature range Operating humidity range -55 °C to +85°C (Note 1)   Relative humidity 90% max. (No condensation) No	Storage temperature range -10°C to +50°C (Note 2) Storage humidity range Relative humidity 90% max.
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Recommended FPC :

Thickness: =  $0.2\pm0.03$ mm tin-lead plated (Note 3)

Item	Specification	Conditions
1. Insulation resistance	50 M ohms min.	100 V DC
2. Withstanding voltage	No flashover or insulation breakdown.	90 V AC /one minute
3. Contact resistance	100 m ohms max. * Including FPC conductor resistance	1 mA
4. Durability (Insertion/ withdrawal)	Contact resistance: 100 m ohms max. No damage, cracks, or parts dislocation.	10 cycles
5. Vibration	No electrical discontinuity of 1µs or more. Contact resistance: 100 m ohms max. No damage, cracks, or parts dislocation.	Frequency: 10 to 55 Hz, single amplitude of 0.75 mm, 10 cycles, 3 directions.
6. Shock	No electrical discontinuity of 1µs. min. Contact resistance: 100 m ohms max. No damage, cracks, or parts dislocation.	Acceleration of 981 m/s <sup>2</sup> , 6 ms duration, sine half-wave waveform, 3 cycles in each of the 3 axis
7. Humidity (Steady state)	Contact resistance: 100 m ohms max. Insulation resistance: 50 M ohms min. No affect on appearance or performance.	96 hours at temperature of $40\pm2^{\circ}$ and humidity of 90% to 95%.
8. Temperature cycle	Contact resistance: 100 m ohms max. Insulation resistance: 50 M ohms min. No damage, cracks, or parts looseness.	Temperature: -55 °C→+15°C to +35°C→+85°C→+15°C to +35°C Time: 30 → 2 to 3 → 30 → 2 to 3 (Minutes) 5 cycles
9. Resistance to soldering heat	No deformation of components affecting performance.	Reflow: At the recommended temperature profile Manual soldering: 350°C +/-10°C for 5±1 seconds

Note 1: Includes temperature rise caused by current flow.

Note 2: The term "storage" refers to products stored for long period of time prior to mounting and use. Operating Temperature Range and Humidity range covers non- conducting condition of installed connectors in storage, shipment or during transportation. Note 3: When FPC is gold plated, the connector contacts must be also gold plated: Specify the (05) plating code.

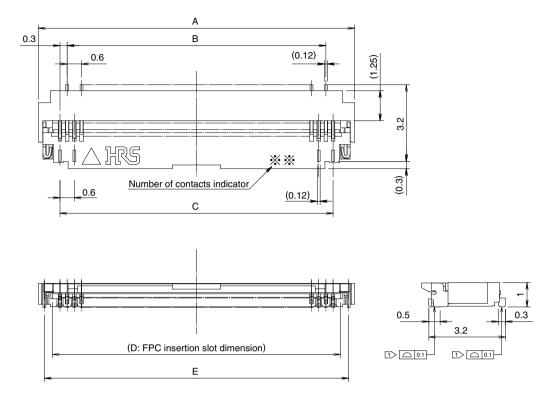
### Materials

Part	Material	Finish	Remarks
Insulator	Poliamide, LCP	Color: Black	
Actuator	PA	Color: Dark brown	UL94V-0
Contacts	Dhoonhor bronzo	Tin-lead plated (Note 3)	
Metal fitting	Phosphor bronze	Tin plated (Lead free)	

### Ordering information

FH26 - 51S -	0.3 SHW (05)
0 2	8 4 6
Series name: FH26	Terminal type: SHW(SMT horizontal mounting)
No. of contacts: 13, 21, 23, 25, 27, 33, 35, 39, 41, 45, 51, 57, 71	OPlating specifications Blank: Tin-lead plated
S Contact pitch: 0.3mm	(05) : Gold flash plated

### **Connector Dimensions**



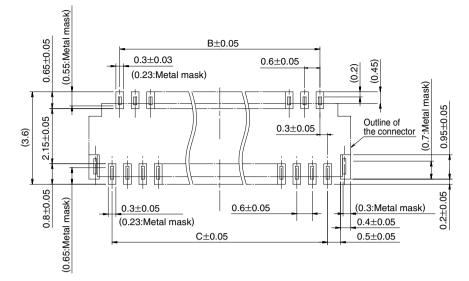
Notes  $\boxed{1}$  The coplanarity of each terminal lead within specified dimension is  $\pm$  0.1 mm.

2 Packaged on tape and reel only. Check packaging specification.

Part Number	CL No.	Number of Contacts	А	В	С	D	E
FH26-13S-0.3SHW	CL580-0209-3	13	5.4	3.0	3.6	4.23	4.9
FH26-21S-0.3SHW	CL580-0207-8	21	7.8	5.4	6.0	6.63	7.3
FH26-23S-0.3SHW	CL580-0203-7	23	8.4	6.0	6.6	7.23	7.9
FH26-25S-0.3SHW	CL580-0208-0	25	9.0	6.6	7.2	7.83	8.5
FH26-27S-0.3SHW	CL580-0204-0	27	9.6	7.2	7.8	8.43	9.1
FH26-33S-0.3SHW	CL580-0210-2	33	11.4	9.0	9.6	10.23	10.9
FH26-35S-0.3SHW	CL580-0205-2	35	12.0	9.6	10.2	10.83	11.5
FH26-39S-0.3SHW	CL580-0201-1	39	13.2	10.8	11.4	12.03	12.7
FH26-41S-0.3SHW	CL580-0206-5	41	13.8	11.4	12.0	12.63	13.3
FH26-45S-0.3SHW	CL580-0211-5	45	15.0	12.6	13.2	13.83	14.5
FH26-51S-0.3SHW	CL580-0200-9	51	16.8	14.4	15.0	15.63	16.3
FH26-57S-0.3SHW	CL580-0212-8	57	18.6	16.2	16.8	17.43	18.1
FH26-71S-0.3SHW	CL580-0202-4	71	22.8	20.4	21.0	21.63	22.3

Embossed tape reel packaging (5,000 pieces/reel). Order by number of reels.

### Recommended PCB mounting pattern and metal mask dimensions



#### Detail H Recommended FPC Dimensions (Lead plated 0.1 MAX) F±0.05 0.3±0.07 C±0.03 0.3±0.07 0±0.03 .1±0.1 . +i (0.15) 10.2 May 0.6±0.02 0.3+0.04 0.3±0.1 1.1±0.1 0.3±0.02 1±0.1 0.2±0.03 B Н 2.25±0.1 3.5 MIN.(Stiffener) 2.1±0.1 2.5±0.3 (2.5) i))i/i (0.5) 0.5min. 0.1±0.02 0.3+0.04 Θ (0.2) (0.2) (0.07) 0.6±0.07 0.6±0.07 B±0.03

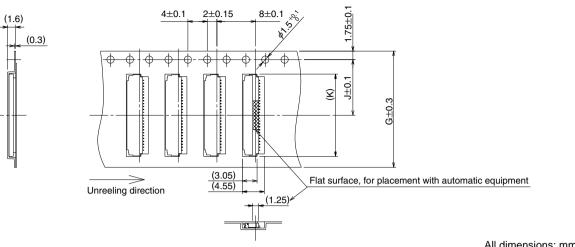
 $\boxed{1}$  Overlap between covering film layer and stiffener.

					All dimensions: mm
Part Number	CL No.	Number of Contacts	В	С	F
FH26-13S-0.3SHW	CL580-0209-3	13	3.0	3.6	4.2
FH26-21S-0.3SHW	CL580-0207-8	21	5.4	6.0	6.6
FH26-23S-0.3SHW	CL580-0203-7	23	6.0	6.6	7.2
FH26-25S-0.3SHW	CL580-0208-0	25	6.6	7.2	7.8
FH26-27S-0.3SHW	CL580-0204-0	27	7.2	7.8	8.4
FH26-33S-0.3SHW	CL580-0210-2	33	9.0	9.6	10.2
FH26-35S-0.3SHW	CL580-0205-2	35	9.6	10.2	10.8
FH26-39S-0.3SHW	CL580-0201-1	39	10.8	11.4	12.0
FH26-41S-0.3SHW	CL580-0206-5	41	11.4	12.0	12.6
FH26-45S-0.3SHW	CL580-0211-5	45	12.6	13.2	13.8
FH26-51S-0.3SHW	CL580-0200-9	51	14.4	15.0	15.6
FH26-57S-0.3SHW	CL580-0212-8	57	16.2	16.8	17.4
FH26-71S-0.3SHW	CL580-0202-4	71	20.4	21.0	21.6



### Packaging Specification

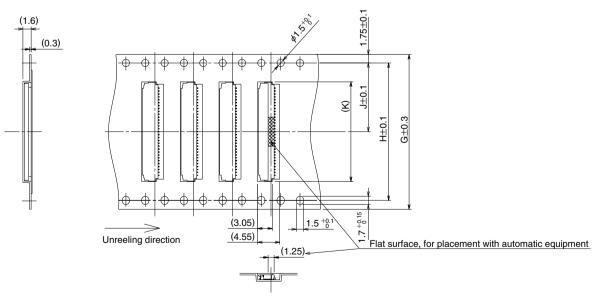
#### Embossed Carrier Tape Dimensions (Tape width of 24mm max.)



					A	Il dimensions: mm
Part Number	CL No.	Number of Contacts	G	J	к	L
FH26-13S-0.3SHW	CL580-0209-3	13	16	7.5	5.6	16.5
FH26-21S-0.3SHW	CL580-0207-8	21	16	7.5	8.0	16.5
FH26-23S-0.3SHW	CL580-0203-7	23	16	7.5	8.6	16.5
FH26-25S-0.3SHW	CL580-0208-0	25	16	7.5	9.2	16.5
FH26-27S-0.3SHW	CL580-0204-0	27	16	7.5	9.8	16.5
FH26-33S-0.3SHW	CL580-0210-2	33	24	11.5	11.6	24.5
FH26-35S-0.3SHW	CL580-0205-2	35	24	11.5	12.2	24.5
FH26-39S-0.3SHW	CL580-0201-1	39	24	11.5	13.4	24.5
FH26-41S-0.3SHW	CL580-0206-5	41	24	11.5	14.0	24.5
FH26-45S-0.3SHW	CL580-0211-5	45	24	11.5	15.2	24.5
FH26-51S-0.3SHW	CL580-0200-9	51	24	11.5	17.0	24.5

5, 000 pieces per reel.

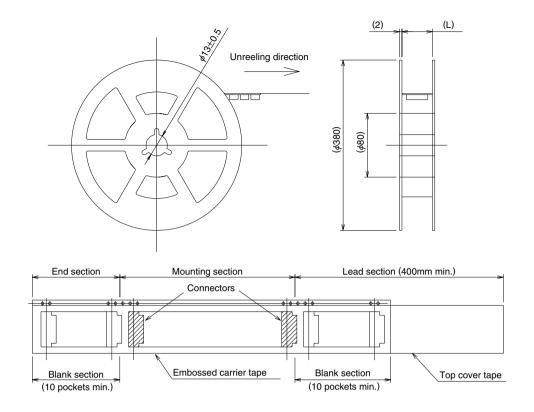
#### •Embossed Carrier Tape Dimensions (Tape width of 32mm min.)



All dimensions: mm

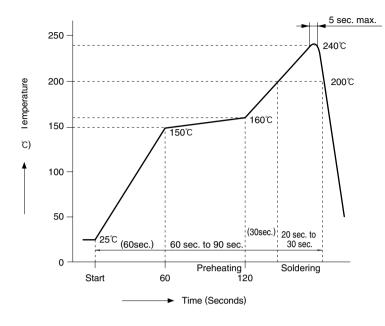
Part Number	CL No.	Number of Contacts	G	Н	J	К	L
FH26-57S-0.3SHW	CL580-0212-8	57	32	28.4	14.2	18.8	32.5
FH26-71S-0.3SHW	CL580-0202-4	71	44	40.4	20.2	23.0	44.5

#### Reel Dimensions



### Recommended Temperature Profile

#### •Using Typical Solder Paste

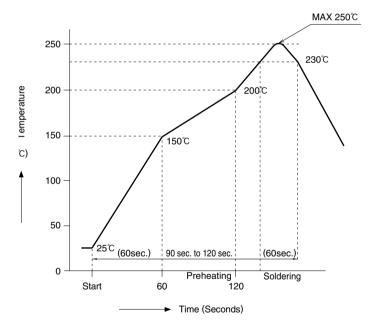


#### **HRS test conditions**

Solder method	:Reflow, IR/hot air
	(Nihon Den-netsu Co., Ltd.'s
	Part Number: SENSBY NR- ${\mathbb I}$ )
Environment:	:Room air
Solder composition:	:Paste, 63%Sn/37%Pb
	(Senju Metal Industry, Co., Ltd.'s
	Part Number: OZ63-201C-50-9)
Test board	:Glass epoxy 25mm×50mm×0.8mm thick
Land dimensions	:0.3mm×0.65mm,0.3mm×0.8mm
Metal mask	:0.23×0.55×0.1mm thick,
	0.23×0.65×0.1mm thick

The temperature profiles are based on the above conditions. In individual applications the actual temperature may vary,depending on solder paste type, volume/thickness and board size/thickness. Consult your solder paste and equipment manufacturer for specific recommendations.

#### Using Lead-free Solder Paste



#### **HRS** test conditions

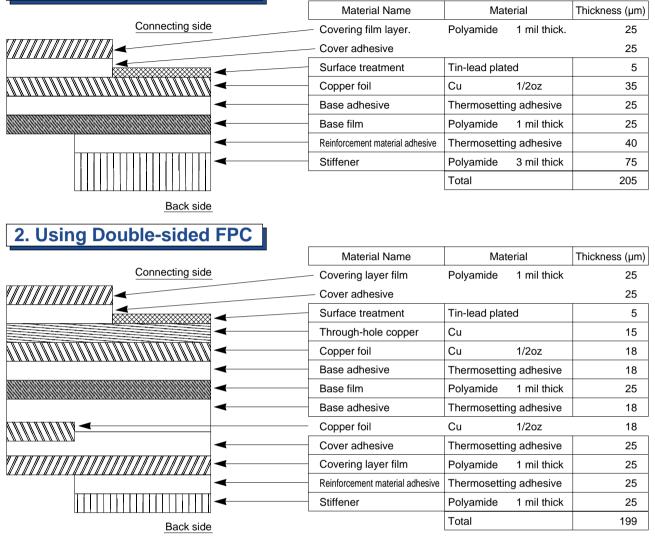
The lest conditions	
Solder method	:Reflow, IR/hot air
	(Nihon Den-netsu Co., Ltd.'s
	Part Number: SENSBY NR-NR- $\mathbbm{I}$ )
Environment	:Room air
Solder composition	:Paste, 96.5%Sn/3.0%Ag/0.5%Cu
	(Senju Metal Industry, Co., Ltd.'s
	Part Number: M705-221CM5-42-10.5)
Test board	:Glass epoxy 25mm×50mm×0.8mm thick
Land dimensions	:0.3mm×0.65mm, 0.3mm×0.8mm
Metal mask	:0.23×0.55×0.1mm thick,
	0.23×0.65×0.1mm thick

The temperature profiles are based on the above conditions. In individual applications the actual temperature may vary, depending on solder paste type, volume/thickness and board size/thickness. Consult your solder paste and equipment manufacturer for specific recommendations.

## Recommended FPC Construction

•Contact FPC manufacturer for specific details.

### 1. Using Single-sided FPC



●To prevent release of the FPC due to it's bending, use of double sided FPC with copper foil on the back side is NOT RECOMMENDED.

### Operation and Precautions

